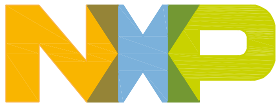

PIN 1 INDEX (LASER MARK)

9

A

2X 2.923

0.1 C 4X

DETAIL E

D

METAL COVER

2X 2.923

9

5X ø0.55 0.45

⌖ Ø 0.6 C A B

Ø 0.2 C

B

MIN. 0.01

D

4.9 4.65

⌖ 0.1 C A B

25 32

PIN 1 INDEX R0.45

24 1

4.9 4.65

⌖ 0.1 C A B

4X 0.325

28X 0.65

17 8

EXPOSED DIE ATTACH PAD

16 9

32X 1.825 1.625

32X 0.4 0.3

⌖ 0.1 Ⓜ C A B

VIEW D–D

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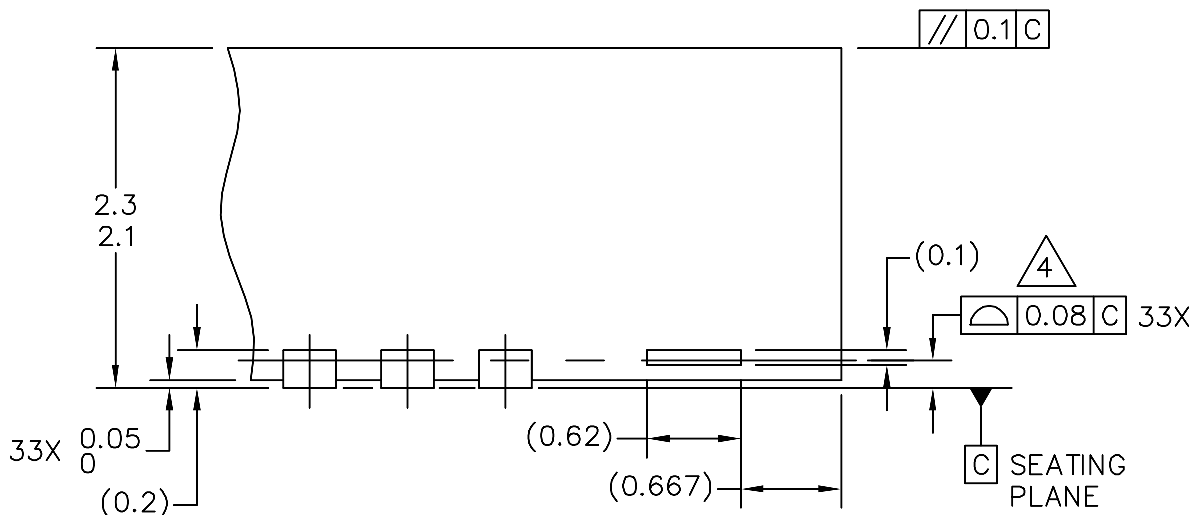
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QFN, THERMALLY ENHANCED, 9 X 9 X 2.2 PKG, 0.65 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA10842D REV: B
	STANDARD: NON–JEDEC
	SOT1576–1 19 JAN 2016



DETAIL E
VIEW ROTATED 90° CW

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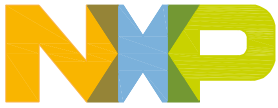
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QFN, THERMALLY ENHANCED, 9 X 9 X 2.2 PKG, 0.65 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA10842D REV: B
	STANDARD: NON-JEDEC
	SOT1576-1 19 JAN 2016



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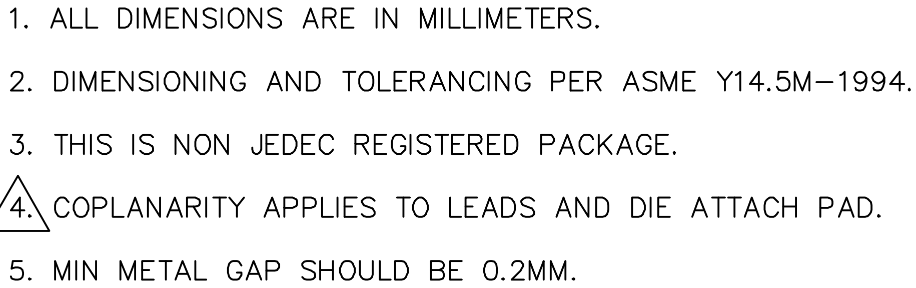

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.
4. (4 in a triangle) COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

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	SOT1576–1	19 JAN 2016